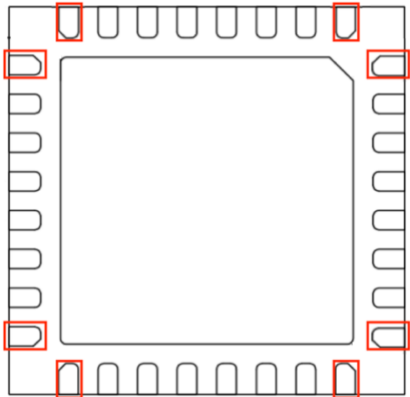
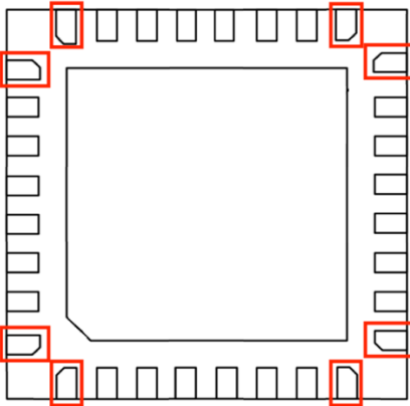
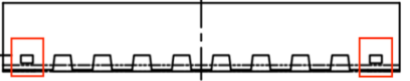
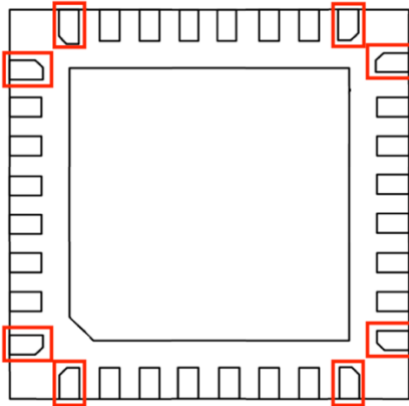
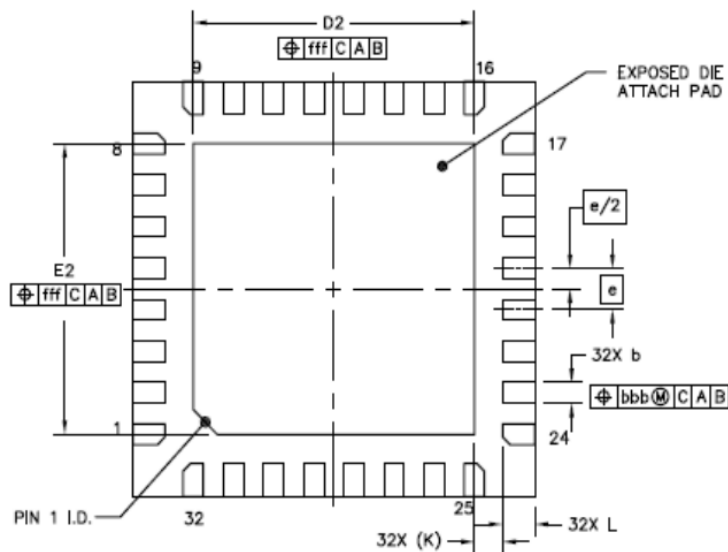
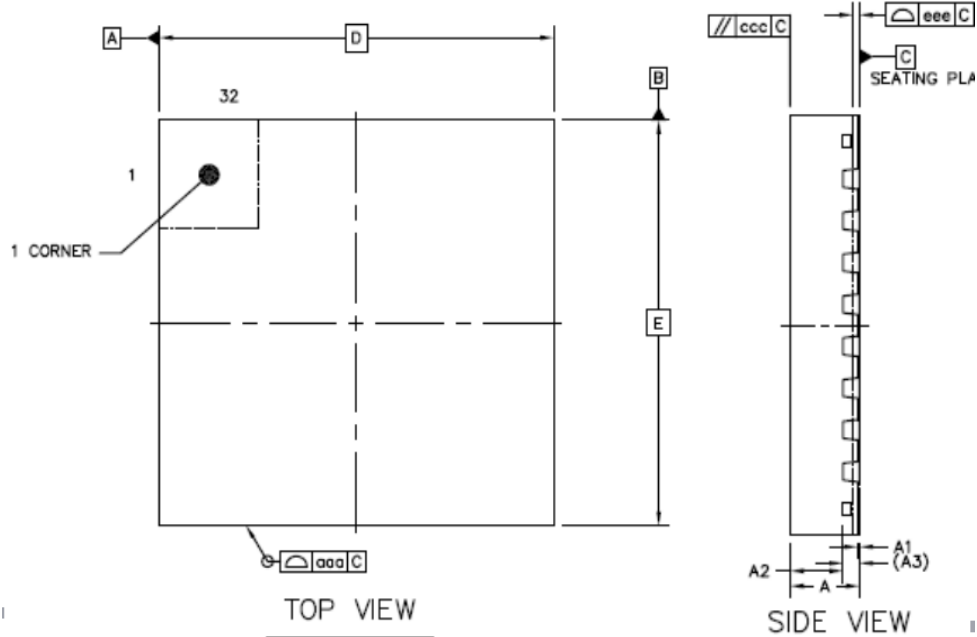


文件编号 Document No.	ESP-00-2-007-03	文件名称 Document Name	产品/工艺变更通知 Product/Process Change Notice (PCN)
文件版本 Document Version	1.1	保存期限 Retention Period	3 年 3 years

增加 ASE 作为 ESP8266EX 芯片的封测厂 Introducing ASE as a new ATM plant for ESP8266EX									
PCN 编号 PCN No.	PCN-03-20200120	提出日期 Issue Date of PCN	2020/2/5						
产品名称 Product Name	ESP8266EX	变更日期 Proposed Date of Change	2020/2/5						
封装类型/尺寸 Package Type/Size	QFN 5X5	首次出货日期 Proposed Date of First Shipment	2020/3/10						
客户批准/Customer Consent: ☒ 需要批准/Approval Required ☐ 通知, 无需批准/Notification, Approval Not Required									
变更等级/Classification of Change: ☒ 主要变更/Major ☐ 轻微变更/Minor									
<u>变更原因/Reason for Change:</u> 为了增加 ESP8266EX 芯片供应链的多样性并提升产能。 In order to diversify the supply chain and increase the production capacity of ESP8266EX chips.									
<u>变更描述/Description of Change:</u> 目前 ESP8266EX 在 Unisem 以及 JCET 进行封装和测试, 为了进一步增强供应链的多样性并提升产能, 因此引入 ASE 作为新的封测厂。 Espressif now has Unisem and JCET to produce ESP8266EX. In order to further diversify the supply chain and improve production capacity, ASE will be introduced as a new Assembly and Test Manufacturing (ATM) plant.									
<u>影响产品/Impacted Products:</u> ESP8266EX									
<u>变更内容/Proposed Change:</u> 引入日月光半导体制造股份有限公司 (ASE) 作为 ESP8266EX 芯片的封测厂。 Introducing ASE Technology Holding Co., Ltd as a new Assembly and Test Manufacturing plant for ESP8266EX.									
<u>变更对比/Before and After the Change:</u> 产品外观图 (Product Appearance Diagram Comparison) <table border="1" style="width: 100%; border-collapse: collapse; margin-top: 10px;"> <tr> <td colspan="3" style="text-align: center;">引脚 Pin Shape</td> </tr> <tr> <td style="width: 33%; text-align: center;">Unisem</td> <td style="width: 33%; text-align: center;">JCET</td> <td style="width: 33%; text-align: center;">ASE</td> </tr> </table>				引脚 Pin Shape			Unisem	JCET	ASE
引脚 Pin Shape									
Unisem	JCET	ASE							

Unisem Chen Du Co., Ltd	江苏省长电科技股份有限公司	日月光半导体制造股份有限公司
引脚顶为弧形。 The top of the pads is circular. 四个边角对应的 8 个引脚顶的形状与其他引脚不同。(见下图) The pads located at the corners of the chip (see pictures below) have different shape from the other pads.  Bottom View 侧视图不同，两侧没有框架连接点。(见下图) The side views are different. There are no joint points of the lead frame at two sides. (see below).  Side View	引脚顶为直线。 The top of the pads is rectangular. 四个边角对应的 8 个引脚顶的形状与其他引脚不同。(见下图) The pads located at the corners of the chip (see pictures below) have different shape from the other pads.  Bottom View 侧视图不同，两侧有框架连接点。(见下图) The side views are different. There are two joint points of the lead frame at two sides. (see below)  Side View	引脚顶为直线。 The top of the pads is rectangular. 四个边角对应的 8 个引脚顶的形状与其他引脚不同。(见下图) The pads located at the corners of the chip (see pictures below) have different shape from the other pads.  Bottom View 侧视图不同，两侧有框架连接点。(见下图) The side views are different. There are two joint points of the lead frame at two sides. (see below)  Side View

尺寸 (Size)



Unit: mm	Unisem Unisem Cheng Du Co., Ltd			JCET 江苏长电科技股份有限公司			ASE ASE Technology Holding Co., Ltd		
尺寸	MIN	NORM	MAX	MIN	NORM	MAX	MIN	NORM	MAX
A	0.8	0.85	0.9	0.8	0.85	0.9	0.8	0.85	0.9
A1	0	-	0.05	0	-	0.05	0	-	0.05
A3	0.203REF.			0.203REF.			0.203REF.		

D	4.95	5	5.05	4.9	5	5.1	4.9	5	5.1
E	4.95	5	5.05	4.9	5	5.1	4.9	5	5.1
D2	3.65	3.7	3.75	3.4	3.5	3.6	3.4	3.5	3.6
E2	3.65	3.7	3.75	3.4	3.5	3.6	3.4	3.5	3.6
b	0.2	0.25	0.3	0.2	0.25	0.3	0.2	0.25	0.3
e	0.5 BSC			0.5 BSC			0.5 BSC		
L	0.35	0.4	0.45	0.3	0.4	0.5	0.3	0.4	0.5
切脚	C0.300×45°			C0.300×45°			C0.300×45°		

变更影响/Impact of Change:

- 在 ASE 生产的 ESP8266EX 产品将在芯片外观上, 包括引脚尺寸和形状与 JCET 完全一致, 但是与 Unisem 略有区别。
The ESP8266EX chips manufactured at ASE are the same in appearance as JCET, while slightly different from Unisem.
- 若客户产线 SMT 贴片模具可以兼容 JCET 生产的 ESP8266EX 芯片, 将能够同时兼容 ASE 生产的芯片。
If the customer's production line SMT mold is compatible with ESP8266EX chip produced by JCET, it will be compatible with ASE chip.

变更前后产品处理/How to Deal with Products:

建议客户同意 PCN 之后再出货由 ASE 生产的 ESP8266EX 芯片。

It is suggested not to deliver ESP8266EX chips manufactured by ASE to the customers until they have approve the PCN.

相关报告/Report(s) Attached:

☒ Related ECN No.: ECN-03-20200120

邮件订阅

Espressif Email Notifications

乐鑫为注册用户提供电子邮件通知服务, 用户可通过[乐鑫订阅系统](#)接收技术文档更新、新闻通讯、PCN 等邮件通知。

Espressif sends email notifications of technical documentation changes, along with newsletters, PCNs and other valuable information, to subscribed customers only. If you wish to stay updated on our products and services, please subscribe [here](#).

客户响应要求

Customer Response Requirements

客户须按照如下要求给予 Espressif PCN 反馈:

Customers are required to respond to Espressif, according to the following guidelines, and confirm receipt of the

PCN:

主要变更/For Major Changes:

- a) 客户须在乐鑫发出 PCN 后的 30 天内告知已收到 PCN。

Customers should confirm receipt of the PCN within 30 calendar days from the date Espressif sends it to them.

- b) 如客户未在接收到 PCN 后的 30 天内告知已收到，则视为客户接受变更。

If customers do not confirm receipt of the PCN within 30 calendar days, they will be regarded as having accepted the proposed changes.

- c) 客户告知确认收到 PCN 后，如未在 90 天内反馈其他要求，则视为客户接受变更。

After the customers confirm receipt of the PCN, the lack of any additional responses on their part within 90 calendar days constitutes acceptance of the proposed changes.

轻微变更/For Minor Changes:

- a) 如客户未在接收到 PCN 后的 7 天内告知已收到，则视为客户接受变更。

If customers do not confirm receipt of the PCN within 7 calendar days, they will be regarded as having accepted the proposed changes.

请反馈至 pcn@espressif.com。

Please send feedback to pcn@espressif.com.

客户批准/确认信息

Customer Approval/Acknowledgement and Remarks

客户公司全称:

Customer's Company Name:

☐ 批准/Approval

PCN 评审结果/PCN Review Result: ☐ 不批准/Disapproval

☐ 需要分析/Further Analysis Required

客户意见/Comment:

公司代表人姓名

Representative's Name:

公司代表人职责

Representative's Job Title:

公司代表人签名

Representative's Signature:

日期

Date: